



Material Content Data Sheet



Sales Product Name		BTS5200-1EJA		Issued		22. January 2018		
MA#		MA001372948						
Package		PG-DSO-8-43		Weight*		84.00 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.977	1.16	1.16	11627	11627
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		112	
	non noble metal	zinc	7440-66-6	0.038	0.04		448	
	non noble metal	iron	7439-89-6	0.752	0.90		8951	
wire	non noble metal	copper	7440-50-8	30.529	36.34	37.29	363450	372961
	non noble metal	copper	7440-50-8	0.193	0.23	0.23	2297	2297
	encapsulation	organic material	carbon black	1333-86-4	0.099	0.12		1179
encapsulation	plastics	epoxy resin	-	4.554	5.42		54213	
	inorganic material	silicondioxide	60676-86-0	44.844	53.41	58.95	533876	589268
leadfinish	non noble metal	tin	7440-31-5	0.824	0.98	0.98	9810	9810
plating	noble metal	silver	7440-22-4	0.726	0.86	0.86	8643	8643
glue	plastics	epoxy resin	-	0.079	0.09		944	
	noble metal	silver	7440-22-4	0.374	0.44	0.53	4450	5394
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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